# **Bluetooth Module Datasheet**

Model: SJR-BTM320

Version: V1.2

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# **1** Introduction

**Sky Jiarun Technologies** introduces the pioneer of the Bluetooth 5.1 modules SJR-BTM320 which is a high performance, cost effective, low power and compact solution. The Bluetooth module provides a complete 2.4GHz Bluetooth system based on the QCC3020 BGA chipset which is a single chip radio and baseband IC for Bluetooth 2.4GHz systems. This module is fully qualified single-chip dual mode Bluetooth@v5.1 system.

### **2 Key Features**

#### BTM320(QCC3020) Features

- Qualified to Bluetooth® v5.1 specification
- 120 MHz Qualcomm® Kalimba™ audio DSPs
- 32 MHz Developer Processor for applications
- Firmware Processor for system
- Flexible QSPI flash programmable platform
- Advanced audio algorithms
- High-performance 24-bit stereo audio interface
- Digital and analog microphone interfaces
- aptX mono, SBC and AAC audio codecs support
- Serial interfaces: UART, Bit Serializer (I<sup>2</sup> C/SPI),USB 2.0
- Integrated PMU: Dual SMPS for system/digital circuits, Integrated Li-ion battery charger

#### **Application subsystem**

- Dual core application subsystem 32 MHz operation
- 32-bit Firmware Processor:
  - Reserved for system use

Runs Bluetooth upper stack, profiles, house-keeping code

- 32-bit Developer Processor:Runs developer applications
- Both cores execute code from external flash memory using QSPI clocked at 32 MHz
- On-chip caches per core allow for optimized performance and power consumption

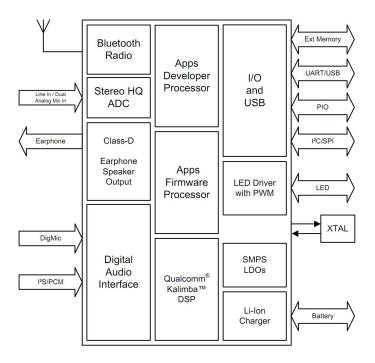
#### Bluetooth subsystem

- Qualified to Bluetooth v5.1 specification including 2 Mbps Bluetooth low energy (Production parts)
- Single ended antenna connection with on-chip balun and Tx/Rx switch
- Bluetooth, Bluetooth low energy, and mixed topologies supported
- Class 1 support

# **3 Applications**

- Wired/wireless stereo headsets/headphones
- Qualcomm TrueWireless<sup>™</sup> stereo earbuds
- USB to Bluetooth dongle

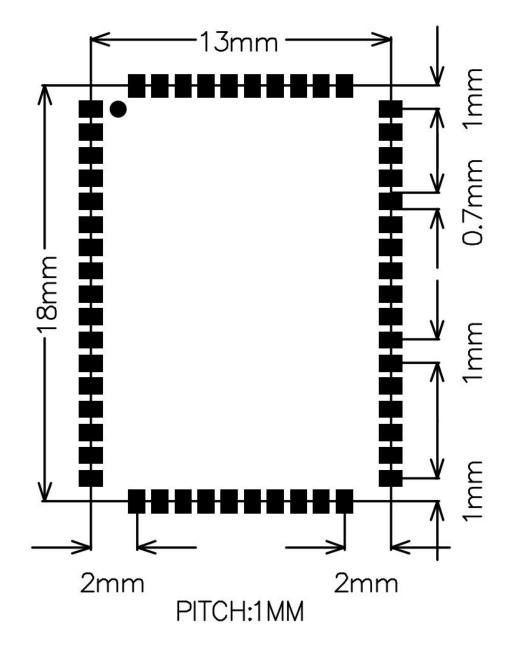
### **4 Block Diagram**



# **5** General specifications

Model Name	SJR-BTM320
<b>Product Description</b>	Bluetooth 5.1 Class1.5 Module
Bluetooth Standard	Bluetooth 5.1
Chipset	QCC3020 BGA
Dimension	13mm x 18mm x 2.8mm
<b>Operating Conditions</b>	
Voltage	2.8~4.3V
Temperature	-40∼+85℃
Storage Temperature	<b>-40∼+85</b> ℃
<b>Electrical Specifications</b>	
Frequency Range	2402~2480MHz
Maximum RF Transmit Power	9dBm
π /4 DQPSK Receive Sensitivity	-92dBm
8DPSK Receive Sensitivity	-85dBm

# **6 Module Package Information**

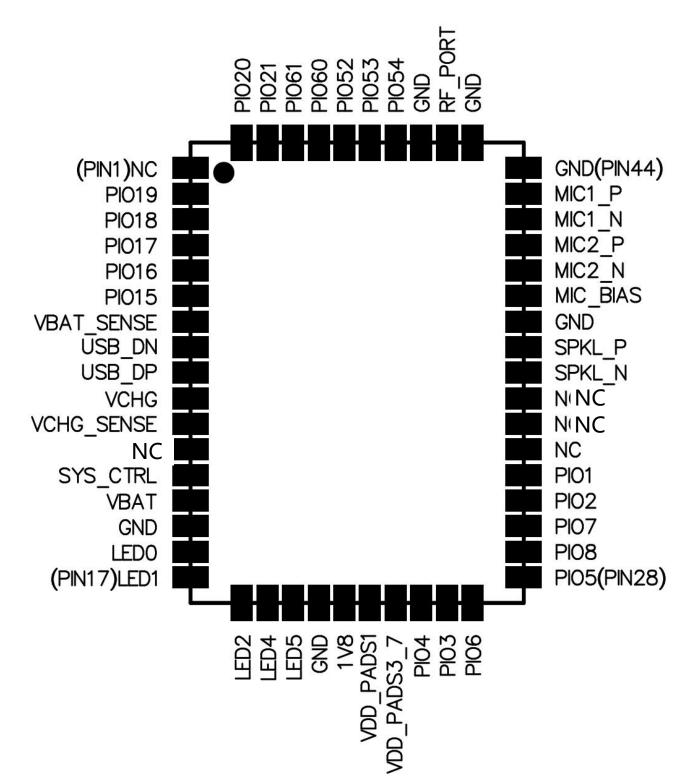


#### **6.1 Pinout Diagram and package dimensions**

Unit: MM

**Recommended PCB layout footprint** 

#### **6.2 Module Pin descriptions**



Pin#	Pin Name	Pin type	Description
1	NC	NC	NC
		Digital: Bidirectional with	Programmable I/O line 19.
2	PIO[19]	programmable strength internal	Alternative function:
		pull- up/pull-down	PCM_DIN[0]
3	PIO[18]	Digital: Bidirectional with	Programmable I/O line 18.

		programmable strength internal	Alternative function:
		pull- up/pull-down	PCM_DOUT[0]
		Digital: Bidirectional with	Programmable I/O line 17.
4	PIO[17]	programmable strength internal	Alternative function:
		pull- up/pull-down	PCM_SYNC
		Digital: Bidirectional with	Programmable I/O line 16.
5	PIO[16]	programmable strength internal	Alternative function:
		pull- up/pull-down	PCM_CLK
		Digital: Bidirectional with	Programmable I/O line 15.
6	PIO[15]	programmable strength internal	Alternative function:
		pull- up/pull-down	MCLK_OUT
7	VBAT_SENSE	Analog	Battery voltage sense input.
			USB Full Speed device D- I/O. IEC-61000-4-2
8	USB_DN	Digital	(device level) ESD Protection
			USB Full Speed device D+ I/O. IEC-61000-4-2
9	USB_DP	Digital	(device level) ESD Protection
10	VCHG	Supply	Charger input to Bypass regulator.
			Charger input sense pin after external mode
			sense-resistor. High impedance.
11	VCHG_SENSE	Analog	
	—		NOTE If using internal charger or no charger,
			connect VCHG_SENSE direct to VCHG.
12	NC	NC	NC
			Typically connected to an ON/OFF push button.
			Boots device in response to a button press when
			power is still present from battery and/or charger but
			software has placed the device in the OFF or
13	SYS_CTRL	Digital input	DORMANT state. Additionally useable as a digital
			input in normal operation. No pull.
			Additional function:
			PIO[0] input only
14	VBAT	Supply	Battery voltage input.
15	GND	Ground	Ground
		Analog or digital input/ open drain	General-purpose analog/digital input or open drain
16	AIO[0]/LED[0]	output.	LED output.
		Analog or digital input/ open drain	General-purpose analog/digital input or open drain
17	AIO[1]/LED[1]	output.	LED output.
		Analog or digital input/ open drain	General-purpose analog/digital input or open drain
18	AIO[2]/LED[2]	output.	LED output.
		Analog or digital input/ open drain	General-purpose analog/digital input or open drain
19	AIO[4]/LED[4]	output.	LED output.
		Analog or digital input/ open drain	General-purpose analog/digital input or open drain
20	AIO[5]/LED[5]	output.	LED output.
		Ground	Ground
21	GND		
	GND 1V8	Supply	1.8V voltage output.

23	VDD_PADS1	Supply	1.8 V/3.3 V PIO supply.
24	VDD_PADS3_7	Supply	1.8 V/3.3 V PIO supply.
		Digital: Bidirectional with	Programmable I/O line 4.
25	PIO[4]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_MOSI[1]
		Digital: Bidirectional with	Programmable I/O line 3.
26	PIO[3]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_MISO[2]
		Digital: Bidirectional with	Programmable I/O line 6.
27	PIO[6]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_MOSI[0]
		Digital: Bidirectional with	Programmable I/O line 5.
28	PIO[5]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_MISO[1]
		Digital: Bidirectional with	Programmable I/O line 8.
29	PIO[8]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_CLK
		Digital: Bidirectional with	Programmable I/O line 7.
30	PIO[7]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_MISO[0]
		Digital: Bidirectional with	Programmable I/O line 2.
31	PIO[2]	programmable strength internal	Alternative function:
		pull- up/pull-down	TBR_MISO[3]
			Automatically defaults to RESET# mode when the
		Digital: Bidirectional with	device is unpowered, or in off modes.
32	PIO[1]	programmable strength internal	Reconfigurable as a PIO after boot.
		pull- up/pull-down	Alternative function:
			Programmable I/O line 1
33	NC	NC	NC
34	NC	NC	NC
35	NC	NC	NC
			Headphone/speaker differential left output,
200			negative.
36	AUDIO_HPL_N/ SPKL_N	Analog	Alternative function:
			Differential left line output, negative
			Headphone/speaker differential left output, positive.
37	AUDIO_HPL_P/ SPKL_P	Analog	Alternative function:
			Differential left line output, positive
38	GND	Ground	Ground
39	AUDIO_MIC_BIAS	Analog	Mic bias output.
			Microphone differential 2 input, negative.
40	AUDIO_MIC2_N/ LINEIN_R_N	Analog	Alternative function:
			Differential audio line input right, negative
			Microphone differential 2 input, positive.
41	AUDIO_MIC2_P/ LINEIN_R_P	Analog	Alternative function:

			Differential audio line input right, positive
			Microphone differential 1 input, negative.
42	AUDIO_MIC1_N/ LINEIN_L_N	Analog	Alternative function:
			Differential audio line input left, negative
			Microphone differential 1 input, positive.
43	AUDIO_MIC1_P/ LINEIN_L_P	Analog	Alternative function:
			Differential audio line input left, positive
44	GND	Ground	Ground
45	GND	Ground	Ground
46	BT_RF	RF	Bluetooth transmit/receive.
47	GND	Ground	Ground
		Digital: Bidirectional with	Programmable I/O line 54.
48	PIO[54]	programmable strength internal	Alternative function:
		pull- up/pull-down	SDIO_D[0]
		Digital: Bidirectional with	Programmable I/O line 53.
49	PIO[53]	programmable strength internal	Alternative function:
		pull- up/pull-down	SDIO_CMD
		Digital: Bidirectional with	Programmable I/O line 52.
50	PIO[52]	programmable strength internal	Alternative function:
		pull- up/pull-down	SDIO_CLK
		Digital: Bidirectional with	
51	PIO[60]	programmable strength internal	Programmable I/O line 60.
		pull- up/pull-down	
		Digital: Bidirectional with	
52	PIO[61]	programmable strength internal	Programmable I/O line 61.
		pull- up/pull-down	
		Digital: Bidirectional with	Programmable I/O line 21.
53	PIO[21]	programmable strength internal	Alternative function:
		pull- up/pull-down	PCM_DOUT[2]
		Digital: Bidirectional with	Programmable I/O line 20.
54	PIO[20]	programmable strength internal	Alternative function:
		pull- up/pull-down	PCM_DOUT[1]

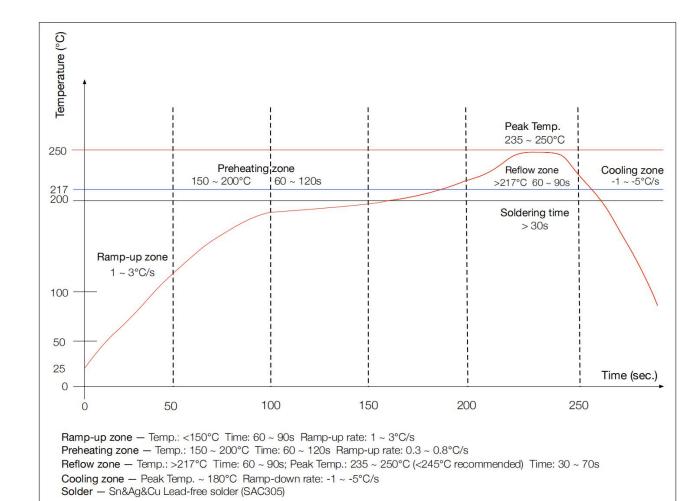
# **7 Electrical Characteristics**

#### 7.1 Absolute Maximum Ratings

Rating	Minimum	Maximum
Storage temperature	<b>-40</b> ℃	<b>+85</b> ℃

#### 7.2 Recommended Operating Conditions

Operating Condition	Minimum	Maximum
Operating temperature range	<b>-40</b> ℃	<b>+85</b> ℃
Supply voltage: VBAT	+2.8V	+4.3V



### **8 Recommended reflow temperature profile**

The module Must go through 125  $^\circ\!\!\!\!^{\rm C}$  baking for at least 9 hours before SMT AND IR reflow process!

若拆封后未立即上线, 天嘉润科技建议让下次上线前务必以 125℃烘烤 9 小时以上!

Data	Revision	Description
2019-06-04	V1.0	Original publication of this document.
2020-04-23	V1.1	Fix PIN definition.
2021-11-21	V1.1	Updata bluetooth 5.1 version and temperature.

### **Record of Changes**

### **IMPORTANT NOTICE**

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